

Electronic Patent Application Fee Transmittal

Application Number:	10583149			
Filing Date:	16-Jun-2006			
Title of Invention:	Method for bonding plastic micro chip			
First Named Inventor/Applicant Name:	Jun Keun Chang			
Filer:	Roger Lowen Browdy/Lynn McGee			
Attorney Docket Number:	CHANG=223			
Filed as Small Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	2614	1	110	110
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	2801	1	405	405
Total in USD (\$)				515